Product Change Notification

Change Notification #:	**116511 - 01**
Change Title:	**Select Intel® SSD E 6100p Series Products, PCN 116511-01, Product Design, Firmware Update** **Reason for Revision: Updating Ready to Receive date**
Date of Publication:	**October 15, 2018**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	January 21, 2019

Description of Change to the Customer:

Reason for Revision: Updating Ready to Receive date

The Intel® SSD E 6100p Series firmware version is being updated from 001E to 004E. The changes in the new firmware version are incremental improvements from previous version. Inventory will transition in the Intel factory on or beyond the above date to replace older firmware version with the latest version.

Customer Impact of Change and Recommended Action:

Since the firmware update has incremental improvement over the previous version, Intel anticipates no product impact with this firmware, and re-qualification is not recommended.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change SA	Post Change TA	Post Change SA
Intel® SSD E 6100p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Generic Single Pack	SSDPEKKR128G801	963756	J85536-100	J86480-100	J85536-101	J86480-101
Intel® SSD E 6100p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Generic Single Pack	SSDPEKKR256G801	963758	J85537-100	J86481-100	J85537-101	J86481-101
Intel® SSD E 6100p Series (128GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Generic 10 Pack	SSDPEKKR128G810	963759	J85538-100	J86480-100	J85538-101	J86480-101
Intel® SSD E 6100p Series (256GB, M.2 80mm PCIe 3.0 x4, 3D2, TLC) Generic 10 Pack	SSDPEKKR256G810	963760	J85539-100	J86481-100	J85539-101	J86481-101

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
October 1, 2018	00	Originally Published PCN
October 15, 2018	01	Updating Ready to Receive date

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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